

## PRELIMINARY AMENDMENT

*In the Claims*

Please add the following claims:

-- 16. A method of manufacturing a semiconductor device comprising the steps of:  
forming a semiconductor film comprising amorphous silicon on an insulating surface;  
forming a film comprising germanium in contact with said semiconductor film by vapor  
phase deposition with a germanium compound gas;  
heating said semiconductor film with said film comprising germanium to crystallize said  
semiconductor film.

17. The method according to claim 16 wherein said film comprising germanium is  
formed by LPCVD.

18. The method according to claim 16 wherein said germanium containing gas is  
 $\text{GeH}_4$ .

19. The method according to claim 16 further comprising a step of removing said film  
comprising germanium after the crystallization of said semiconductor film.

20. A method of manufacturing a semiconductor device comprising the steps of:  
forming a semiconductor film comprising amorphous silicon on an insulating surface;  
forming a film comprising germanium in contact with said semiconductor film by vapor  
phase deposition with a germanium compound gas;  
heating said semiconductor film with said film comprising germanium to crystallize said  
semiconductor film;  
patterning the crystallized semiconductor film into at least one semiconductor island;  
forming a thin film transistor with said semiconductor island used as at least a channel  
forming region thereof.

21. The method according to claim 20 wherein said film comprising germanium is formed by LPCVD.

22. The method according to claim 20 wherein said germanium containing gas is  $\text{GeH}_4$ .

23. ~~The method according to claim 20 further comprising a step of removing said film comprising germanium after the crystallization of said semiconductor film.~~

24. The method according to claim 5 wherein said semiconductor device is a video camera.

25. The method according to claim 5 wherein said semiconductor device is a mobile computer.

26. The method according to claim 5 wherein said semiconductor device is a portable telephone.

27. The method according to claim 5 wherein said semiconductor device is a head mount display.

28. The method according to claim 5 wherein said semiconductor device is a projector.

29. The method according to claim 16 wherein said semiconductor device is a video camera.

30. The method according to claim 16 wherein said semiconductor device is a mobile computer.

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31. The method according to claim 16 wherein said semiconductor device is a portable telephone.

32. The method according to claim 16 wherein said semiconductor device is a head mount display.

A 33. The method according to claim 16 wherein said semiconductor device is a projector.

34. The method according to claim 20 wherein said semiconductor device is a video camera.

35. The method according to claim 20 wherein said semiconductor device is a mobile computer.

36. The method according to claim 20 wherein said semiconductor device is a portable telephone.

37. The method according to claim 20 wherein said semiconductor device is a head mount display.

38. The method according to claim 20 wherein said semiconductor device is a projector.--

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